Shao-Yun Fang

List of Publications by Year in descending order

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1478505 1281871 35 307 11 6 citations h-index g-index papers 35 35 35 171 docs citations times ranked citing authors all docs

| # | Article | IF | CITATIONS |
|----|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----|-----------|
| 1 | RouteNet., 2018,,. | | 119 |
| 2 | A Novel Layout Decomposition Algorithm for Triple Patterning Lithography. IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, 2014, 33, 397-408. | 2.7 | 50 |
| 3 | Pin Accessibility Prediction and Optimization with Deep Learning-based Pin Pattern Recognition. , 2019, , | | 23 |
| 4 | Device Array Layout Synthesis With Nonlinear Gradient Compensation for a High-Accuracy Current-Steering DAC. IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, 2018, 37, 717-728. | 2.7 | 16 |
| 5 | From IC Layout to Die Photograph: A CNN-Based Data-Driven Approach. IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, 2021, 40, 957-970. | 2.7 | 13 |
| 6 | Simultaneous guiding template optimization and redundant via insertion for directed self-assembly. , 2015, , . | | 11 |
| 7 | Cut mask optimization with wire planning in self-aligned multiple patterning full-chip routing. , 2015, , . | | 10 |
| 8 | Graph-Based Subfield Scheduling for Electron-Beam Photomask Fabrication. IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, 2013, 32, 189-201. | 2.7 | 8 |
| 9 | Simultaneous Guiding Template Optimization and Redundant via Insertion for Directed Self-Assembly. IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, 2017, 36, 156-169. | 2.7 | 7 |
| 10 | Simultaneous template assignment and layout decomposition using multiple bcp materials in DSA-MP lithography. , $2017, \ldots$ | | 7 |
| 11 | Pin Accessibility Prediction and Optimization With Deep-Learning-Based Pin Pattern Recognition. IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, 2021, 40, 2345-2356. | 2.7 | 7 |
| 12 | Stitch-Aware Routing for Multiple E-Beam Lithography. IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, 2015, 34, 471-482. | 2.7 | 5 |
| 13 | Deep learning-based framework for comprehensive mask optimization. , 2019, , . | | 5 |
| 14 | Design optimization considering guiding template feasibility and redundant via insertion for directed self-assembly. , 2016, , . | | 4 |
| 15 | Guiding template-aware routing considering redundant via insertion for directed self-assembly. , 2017, | | 3 |
| 16 | Flip-Chip Routing With I/O Planning Considering Practical Pad Assignment Constraints. IEEE Transactions on Very Large Scale Integration (VLSI) Systems, 2019, 27, 1921-1932. | 3.1 | 3 |
| 17 | Flip-chip routing with IO planning considering practical pad assignment constraints. , $2018, \ldots$ | | 2 |
| 18 | Provably Good Max–Min-\$m\$-Neighbor-TSP-Based Subfield Scheduling for Electron-Beam Photomask Fabrication. IEEE Transactions on Very Large Scale Integration (VLSI) Systems, 2018, 26, 378-391. | 3.1 | 2 |

| # | Article | IF | Citations |
|----|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----|-----------|
| 19 | Printability Enhancement with Color Balancing for Multiple Patterning Lithography. IEEE Transactions on Emerging Topics in Computing, 2019, 7, 244-252. | 4.6 | 2 |
| 20 | Provably good max-min-m-neighbor-TSP-based subfield scheduling for electron-beam photomask fabrication. , $2015, , .$ | | 1 |
| 21 | Overlay-aware layout legalization for self-aligned double patterning lithography. , 2016, , . | | 1 |
| 22 | Trim mask optimization for hybrid multiple pattering lithography. , 2016, , . | | 1 |
| 23 | Cut Mask Optimization With Wire Planning in Self-Aligned Multiple Patterning Full-Chip Routing. IEEE Transactions on Very Large Scale Integration (VLSI) Systems, 2017, 25, 581-593. | 3.1 | 1 |
| 24 | Obstacle-Avoiding Open-Net Connector with Precise Shortest Distance Estimation*., 2018,,. | | 1 |
| 25 | Triple patterning lithography-aware detailed routing ensuring via layer decomposability. , 2018, , . | | 1 |
| 26 | Obstacle-Avoiding Open-Net Connector With Precise Shortest Distance Estimation. IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, 2020, 39, 1096-1108. | 2.7 | 1 |
| 27 | Stitch-Aware Routing Considering Smart Boundary for Multiple E-Beam Lithography. , 2020, , . | | 1 |
| 28 | Manufacturability Enhancement With Dummy via Insertion for DSA-MP Lithography Using Multiple BCP Materials. IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, 2021, 40, 400-404. | 2.7 | 1 |
| 29 | Demand-Driven Multi-Target Sample Preparation on Resource-Constrained Digital Microfluidic Biochips. ACM Transactions on Design Automation of Electronic Systems, 2022, 27, 1-21. | 2.6 | 1 |
| 30 | Design Optimization Considering Guiding Template Feasibility and Redundant Via Insertion for Directed Self-Assembly. IEEE Transactions on Circuits and Systems I: Regular Papers, 2017, 64, 3172-3182. | 5.4 | 0 |
| 31 | PlanarONoC: Concurrent Placement and Routing Considering Crossing Minimization for Optical Networks-on-Chip. , 2018, , . | | O |
| 32 | Guiding Template-Induced Design Challenges in DSA-MP Lithography. , 2018, , . | | 0 |
| 33 | Obstacle-Avoiding Length-Matching Bus Routing Considering Nonuniform Track Resources. IEEE Transactions on Very Large Scale Integration (VLSI) Systems, 2020, 28, 1881-1892. | 3.1 | 0 |
| 34 | Placement-guided pin layout substitution for routability optimization. Microelectronics Journal, 2021, 114, 105151. | 2.0 | 0 |
| 35 | COALA: Concurrently Assigning Wire Segments to Layers for 2-D Global Routing. IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, 2023, 42, 569-582. | 2.7 | O |